

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Decommission of Newport, Wales wafer fab, as announced by the corporation on May 5th 2015

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **22-May-2017**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates:
“**Lack of acknowledgment of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
Postal Address Headquarters: Am Campeon 1-12, D-85579 Neubiberg, Phone +49 (0)89 234-0
Chairman of the Supervisory Board: Wolfgang Mayrhuber
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck
Registered Office: Neubiberg Commercial Register
Amtsgericht München HRB 126492

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► **Products affected:**

Sales Name	SP N°	OPN	Package
IRF2804STRLPBF	SP001561584	IRF2804STRLPBF	D2PAK
IRF2804SPBF	SP001561604	IRF2804SPBF	D2PAK

► **Detailed Change Information:**

Subject: Add Dresden 300MM as qualified Fab for Gen 10.2

Reason: Expansion of wafer production and wafer test capacity.

Description: Decommission of Newport, Wales wafer fab, as announced by the corporation on May 5th 2015

As the result of this change

	OLD	NEW
Wafer Fab Location	Vanguard International Semiconductor or Infineon Technologies Newport Limited	Vanguard International Semiconductor or Infineon Technologies Newport Limited or Infineon Technologies AG, Dresden, Germany

► **Product Identification:** Wafer fab origins will not be distinguished through the external part marking or shipping labels, however, based on the assembly lot code and marked on the device. IFX internal systems will be able to trace the site of the wafer lots used to produce the final product.

► **Impact of Change:** No changes to form, fit, or function. The package outline remains the same. Datasheet specifications will not be changed. The package bill of material and the location for assembly and final test will not change.

► **Attachments:**

► **Time Schedule:**

■ Final qualification report:

Available

■ First samples available:

On request

■ Intended start of delivery:

03-June-2017

If you have any questions, please do not hesitate to contact your local Sales office.